

**IN THE CLAIMS:**

- 1 1. (currently amended) A die containing package comprising:  
2 a die defining electrical die contacts,  
3 a substrate defining first substrate contacts,  
4 flattened electrical conductive balls attached to the die contacts and making  
5 electrical connection thereto,  
6 electrical conductive runs on the substrate connecting the first substrate contacts  
7 to second substrate contacts,  
8 electrically conductive wires with ~~one first ends end connected making electri-~~  
9 cal connections to the first substrate contacts, wherein the wires are formed to run sub-  
10 stantially parallel to the surface of the die ~~to and wherein the other ends are arranged~~  
11 making electrical connections to the flattened electrical conductive balls attached to the  
12 die contacts, and wherein the other ends remain substantially parallel to the surface of  
13 the die as they make electrical connections to the flattened electrical conductive balls;  
14 ~~means for making electrical connection between the die contacts and the other~~  
15 ~~end of the wires.~~
- 1 2. Canceled.
- 1 3. (previously presented) The die containing package of claim 1 wherein the second  
2 substrate contacts are located on the substrate opposite the first substrate contacts.
- 1 4. (previously presented) The die containing package of claim 1 wherein the second  
2 substrate contacts are located on the substrate to accommodate a pin out different from  
3 the die.
- 1 5. (currently amended) A process for packaging a die comprising the steps of:  
2 defining electrical die contacts,

3       defining a substrate with first substrate contacts,  
4       flattening ~~an~~ electrical conductive balls,  
5       attaching the flattened electrically conductive ~~ball~~ balls to the die contacts,  
6       forming electrical conductive runs on the substrate connecting the first substrate  
7 contacts to second substrate contacts,  
8       connecting electrically conductive wires to the first substrate contacts,  
9       running the electrically conductive wires substantially parallel to the surface of  
10 the die to the die contacts, and  
11       making electrical connections from the other ends of the wires to the flattened  
12 electrical conductive balls attached to the die contacts, and wherein the other ends re-  
13 main substantially parallel to the surface of the die as they make electrical connections  
14 to the flattened electrical conductive balls. ~~making electrical connection between the die~~  
15 ~~contacts and the other end of the wires.~~

1   6. Canceled.

1   7. (previously presented) The process of claim 5 further comprising the step of locat-  
2 ing the second substrate contacts on the substrate opposite the first substrate contacts.

1   8. (previously presented) The process of claim 5 further comprising the step of locat-  
2 ing the second substrate contacts on the substrate to accommodate a pin out different  
3 from the die.